



IEEE COMCOMAP 2021

Computing, Communications & IoT Applications Conference

November 26-28, 2021, Shenzhen, China

Sponsor

Southern University of Science and Technology, Shenzhen, China



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IEEE AP-S (Shenzhen Chapter)



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CONFERENCE WEBSITE: <http://ComComAp.net/2021/>

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CALL FOR PAPERS

Submission Deadline: September 15, 2021

You are cordially invited to participate in and attend the **Computing, Communications and IoT Applications Conference (ComComAp 2021)** to be held in Beijing, China, on **November 26-28, 2021**. The conference is to address, explore and exchange information on the state-of-the-art in all types of computing systems, communications, and networking as well as IoT/Engineering applications.

We are interested in visionary, experimental, systems-related and work in-progress papers on the current state of research in Computers, Communications/Networking and IoT/Engineering Applications and related issues. Papers should describe original, previously unpublished work, not currently under review by another conference, workshop, or journal.

Important Dates

Paper Submission

July 15th, 2021

Paper Acceptance

October 15th, 2021

Camera-ready

November 1st, 2021

Registration

November 1st, 2021

Topics include (but are not limited to):

• ANTENNAS AND MICROWAVE/MM-WAVE/THZ DEVICES/CIRCUITS

- Antennas for Mobile Communications
- EM Theory and Applications
- Antennas for Ultra High Data Rate Communications
- Propagation For Location Based Devices
- Antennas and Propagation for Biomedical Apps
- Antennas for Wireless LAN
- Scattering, Diffraction and Padar Cross Section
- Propagation Theory and Measurements
- Environmental Effects on Radio Propagation
- Metasurface Materials and Techniques

• INTERNET OF THINGS (IoT) SERVICES AND APPLICATIONS

- Next Generation IoT
- IoT Devices/Applications
- Multimedia over IoT
- Vehicular Communications over IoT
- Social Networking and IoT
- IoT Security
- IoT QoS and Management
- IoT over 5G
- Cooperative IoT Services
- IoT Green Computing

• WIRELESS COMMUNICATIONS, SMART SYSTEMS, CLOUD/FOG & BIG DATA

- Smart Systems: City, Building, Campus
- Wireless Communications and Networking
- Cyber Physical Systems
- Intelligent Transportation
- Smart Sensors
- Smart Grid and Big Data
- Cloud/Fog Applications
- Cloud/Fog Computing
- Cloud/Fog Communications and Networking
- Smart Robot Technologies

WIRELESS NETWORKS, & NETWORK SECURITY

- Future Network architecture for IoT
- Transmission Optimization
- SDN/NVF for Wireless Networks
- Resource Management for Wireless Networks
- AI Technology for Wireless Network
- Access Control in Wireless Networks
- Blockchain Technology for IoT
- Privacy Preserving Mobile Computing
- Security Protection in Space Information Networks
- Trust Management in Wireless Networks

Paper Submissions

Please submit an electronic copy of your original **full manuscript** (not to exceed 6 double-column IEEE formatted pages, including figures, tables, and references) to: <https://edas.info/XXXXX>

Please clearly indicate the corresponding author. Include up to 6 keywords from the above list and an abstract of no more than 350 words. Papers must be submitted in PDF format only via the above EDAS portal. For more information, visit the conference website: <http://ComComAp.net/2021/>

If you have any questions about paper submissions or the program, please contact any of the listed Program Chairs.

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Note: Accepted and presented technical papers will be submitted to IEEE Xplore and Compendex. In addition, high quality papers will be invited to be submitted to one of 5 Journal Special Issues:

- 1) *International Journal of Antennas and Propagation Journal*
- 2) *International Journal of Information Technology, Communications and Convergence Journal*
- 3) *Peer to Peer Networking & Applications Journal*
- 4) *Journal of Network and Computer Applications Journal*
- 5) *International Journal of Distributed Sensor Networks Journal*

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